

#### 2.0x1.25mm SMD CHIP LED LAMP

Part Number: KP-2012MGC

Mega Green

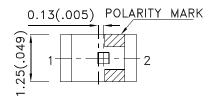
#### **Features**

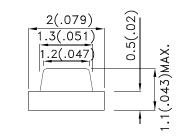
- 2.0mmx1.25mm SMT LED,1.1mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

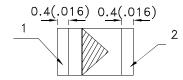
#### Description

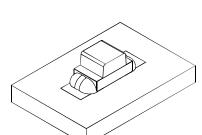
The Mega Green source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

### **Package Dimensions**









#### Notes:

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- All dimensions are in millimeters (inches).
   Tolerance is ±0.1(0.004") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

  4. The device has a single mounting surface. The device must be mounted according to the specifications.

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### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KP-2012MGC	Mega Green (AlGaInP)	WATER CLEAR	36	70	120°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

	<b>F</b>								
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions			
λpeak	Peak Wavelength	Mega Green	574		nm	IF=20mA			
λD [1]	Dominant Wavelength	Mega Green	570		nm	IF=20mA			
Δλ1/2	Spectral Line Half-width	Mega Green	26		nm	IF=20mA			
С	Capacitance	Mega Green	20		pF	V <sub>F</sub> =0V;f=1MHz			
VF [2]	Forward Voltage	Mega Green	2.1	2.5	V	IF=20mA			
lr	Reverse Current	Mega Green		10	uA	V <sub>R</sub> =5V			

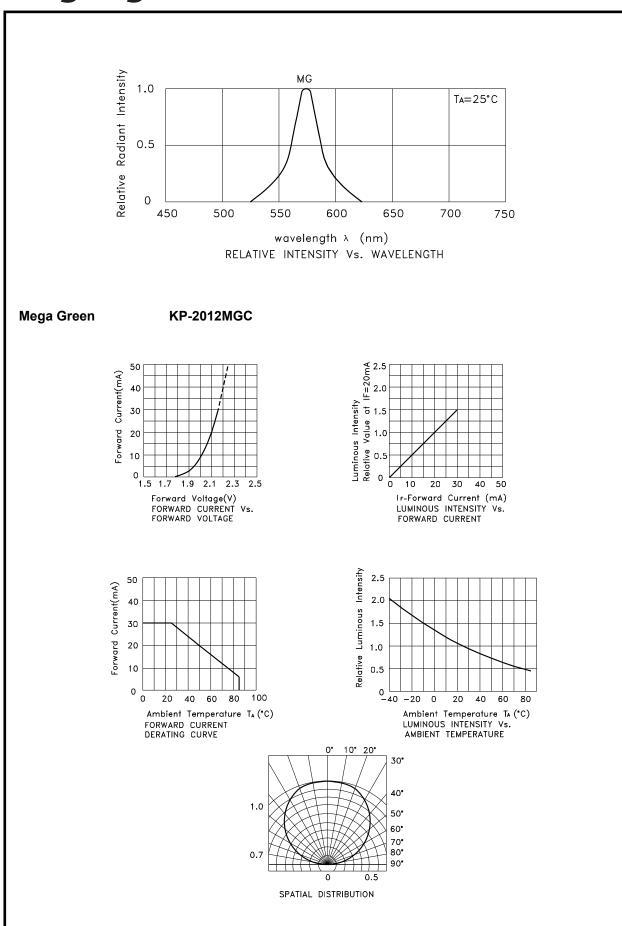
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

#### Absolute Maximum Ratings at TA=25°C

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Parameter	Mega Green	Units			
Power dissipation	75	mW			
DC Forward Current	30	mA			
Peak Forward Current [1]	150	mA			
Reverse Voltage	5	V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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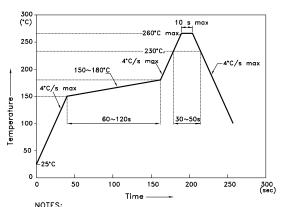
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#### **KP-2012MGC**

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



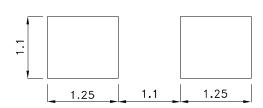
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

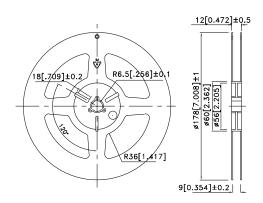
  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
  - to high temperature.

    3.Number of reflow process shall be 2 times or less.

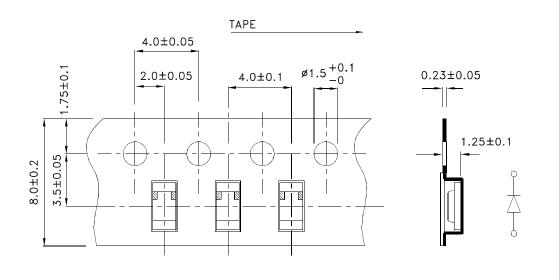
## Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



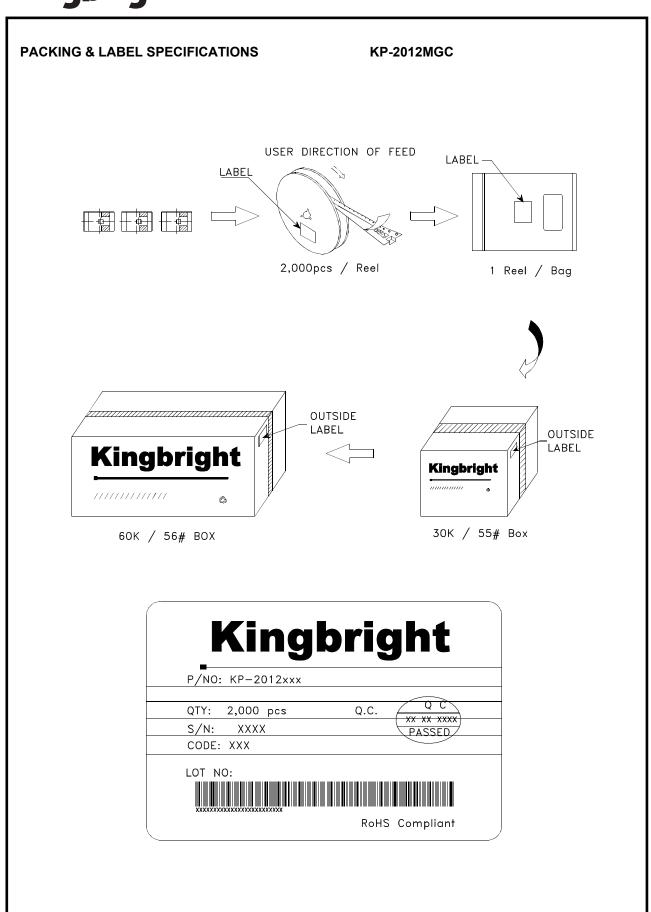
#### **Reel Dimension**



## Tape Dimensions (Units : mm)



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